



Final Product/Process Change Notification  
Document #:FPCN23840XM1  
Issue Date:10 Jan 2022

<b>Title of Change:</b>	Final Product Change Notification - Bump Site Transfer from FCI to JCAP	
<b>Proposed First Ship date:</b>	17 Apr 2022 or earlier if approved by customer	
<b>Contact Information:</b>	Contact your local onsemi Sales Office	
<b>PCN Samples Contact:</b>	<p>Contact your local onsemi Sales Office.</p> <p>Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.</p> <p>Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</p>	
<b>Additional Reliability Data:</b>	Contact your local onsemi Sales Office or <a href="mailto:Joe.Chapple@onsemi.com">Joe.Chapple@onsemi.com</a>	
<b>Type of Notification:</b>	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a></p>	
<b>Marking of Parts/ Traceability of Change:</b>	Parts using the JCAP bump flow will be identified by a new plant code	
<b>Change Category:</b>	Assembly Change, Bump Site Change	
<b>Change Sub-Category(s):</b>	Manufacturing Site Transfer	
<b>Sites Affected:</b>		
<b>onsemi Sites</b>		<b>External Foundry/Subcon Sites</b>
None		Flipchip International, USA
		JCAP, China
<b>Description and Purpose:</b>		
	<b>Before Change Description</b>	<b>After Change Description</b>
Bump Site	Flipchip International, USA	JCAP, China
Structure	1P1M	1P1M
P1 Material	PBO(CRC-2348)	PI HD4100
M1 Material	TiNiVCu	Cu
Solderball Material	SAC266	SAC266



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**Reliability Data Summary:**

QV Device Name: NB3RL02FCT2G

RMS: 75629

Package: WLCSP-8

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/84
TC	JESD22-A104	Ta= -40°C to +125°C	850 cyc	0/84
UHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	5x reflow	0/84
SBS	AEC Q100-010 AEC Q003	CPK >1.67	—	Cpk>1.67
BLR_DT	JESD22-B111	1500G, 0.5ms, half-sine pulse. Peak acceleration : 1500G +/- 10% with Cpk > 1.33. Pulse Duration : 0.5ms +/- 10%.	1000 drops	0/60
BLR_TC		Ta= -40°C to +125°C	450 cyc	0/75

**Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [\*\*PCN Customized Portal\*\*](#).

Part Number	Qualification Vehicle
NB3RL02FCT2G	NB3RL02FCT2G